

#### **Description**

The HD5154 uses advanced trench technology to provide excellent  $R_{\rm DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications

# D S S

#### **General Features**

 $V_{DS} = 20V, I_{D} = 30A$ 

 $R_{DS(ON)}$  < 15 m $\Omega$ @  $V_{GS}$ =4.5V

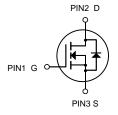
### TO-252-2L

## **Application**

Power switching application

Hard Switched and High Frequency Circuits

Uninterruptible Power Supply



N-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
HD5154	TO-252-2L	HD5154 XXX YYYY	2500

### Absolute Maximum Ratings@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	20	V
VGS	Gate-Source Voltage	<u>+</u> 12	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Drain Current, V <sub>GS</sub> @ 4.5V	30	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Drain Current, V <sub>GS</sub> @ 4.5V	18	А
IDM	Pulsed Drain Current <sup>1</sup>	60	А
PD@Tc=25°C	Total Power Dissipation	5	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	2	W
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>4</sup>	12.1	mJ
TSTG	Storage Temperature Range	-55 to 150	℃
TJ	Operating Junction Temperature Range	-55 to 150	°C
Rthj-c	Maximum Thermal Resistance, Junction-case	5	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	100	°C/W



## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	20	-	-	V
Gate Leakage Current	Igss	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0 V	-	-	±100	nA
Drain Cut-off Current	IDSS	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0 V	-	-	1	μA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250μA	0.45	0.7	1	٧
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> =5A	-	10	15	mΩ
Drain-Source On-State Resistance <sup>3</sup>		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 4.7A	-	17	30	
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 4.3A	-	28	50	
Dynamic Characteristics <sup>4</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 10V, f = 1MHz	-	700	-	pF
Output Capacitance	Coss		-	120	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	105	-	
Switching Characteristics <sup>4</sup>						
Total Gate Charge	Qg		-	10.5	-	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 5A	-	2	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	2.5	-	
Turn-On Time	t <sub>d(on)</sub>		-	10	-	
Rise Time	tr	V <sub>GEN</sub> = 5V, V <sub>DD</sub> = 10V,	-	20	-	ns
Turn-Off Time	t <sub>d(off)</sub>	$I_D = 5A, R_G = 3\Omega,$	-	32	-	
Fall Time	t <sub>f</sub>		-	12	-	
Source-Drain Diode Characteristics						
Body Diode Voltage <sup>3</sup>	V <sub>SD</sub>	I <sub>S</sub> =4A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current	Is		-	-	30	Α

#### Notes:

- 1. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}$ =150°C.
- 2. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 3. Pulse Test: Pulse width≤300µs, duty cycle≤2%.
- 4. This value is guaranteed by design hence it is not included in the production test.



# **Typical Characteristics**

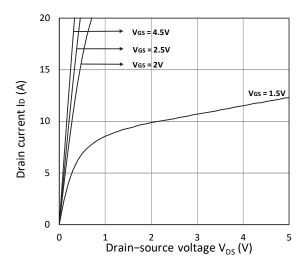


Figure 1. Output Characteristics

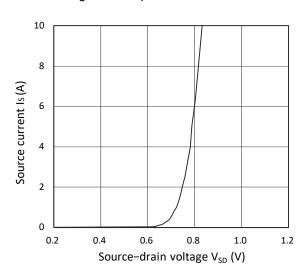


Figure 3. Forward Characteristics of Reverse

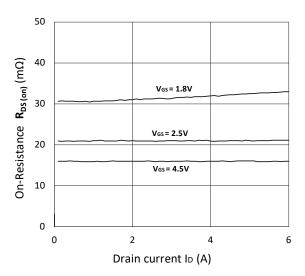


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ 

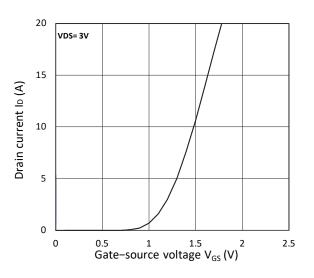


Figure 2. Transfer Characteristics

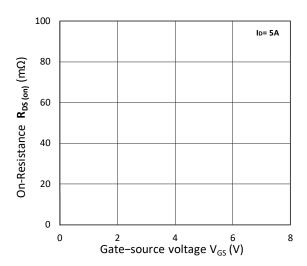


Figure 4.  $R_{\text{DS}(\text{ON})}\,$  vs.  $V_{\text{GS}}$ 

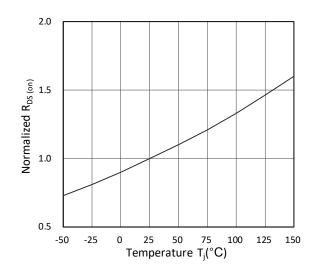
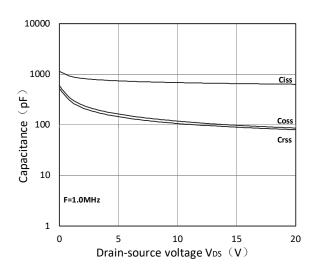
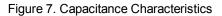


Figure 6. Normalized  $R_{\text{DS(on)}}\,\text{vs.}$  Temperature





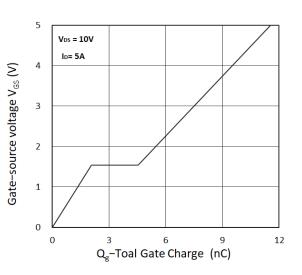
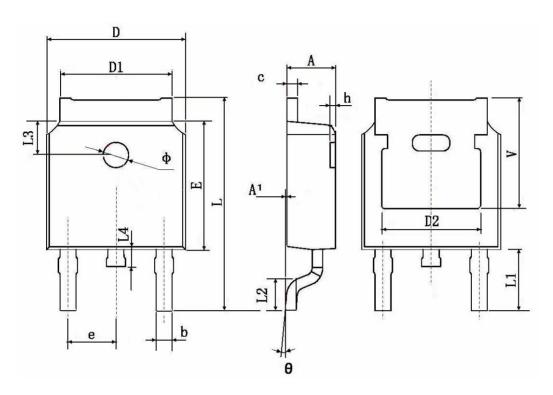


Figure 8. Gate Charge Characteristics



# **TO-252-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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